

# LMH6619Q 130 MHz, 1.25 mA RRIO Operational Amplifier

Check for Samples: LMH6619Q

# FEATURES

- $V_S = 5V$ ,  $R_L = 1 \ k\Omega$ ,  $T_A = 25^{\circ}C$  and  $A_V = +1$ , unless otherwise specified.
- Operating voltage range 2.7V to 11V
- Supply current per channel 1.25 mA
- Small signal bandwidth 130 MHz
- Input offset voltage (limit at 25°C) ±0.75 mV
- Slew rate 55 V/µs
- Settling time to 0.1% 90 ns
- Settling time to 0.01% 120 ns
- SFDR (f = 100 kHz,  $A_V$  = +1,  $V_{OUT}$  = 2  $V_{PP}$ ) 100 dBc
- 0.1 dB bandwidth ( $A_V = +2$ ) 15 MHz
- Low voltage noise 10 nV/√Hz
- Rail-to-Rail input and output

# DESCRIPTION

- AEC-Q100 grade 2 qualified -40°C to +105°C
- Manufactured on an automotive grade flow

# **APPLICATIONS**

- ADC driver
- DAC buffer
- Active filters
- High speed sensor amplifier
- Current sense amplifier
- Portable video
- STB, TV video amplifier
- Automotive

The LMH6619Q (dual) is a 130 MHz rail-to-rail input and output amplifier designed for ease of use in a wide range of applications requiring high speed, low supply current, low noise, and the ability to drive complex ADC and video loads. The operating voltage range extends from 2.7V to 11V and the supply current is typically 1.25 mA per channel at 5V. The LMH6619Q is a member of the PowerWise<sup>®</sup> family and have an exceptional power-to-performance ratio.

The amplifier's voltage feedback design topology provides balanced inputs and high open loop gain for ease of use and accuracy in applications such as active filter design. Offset voltage is typically 0.1 mV and settling time to 0.01% is 120 ns which combined with an 100 dBc SFDR at 100 kHz makes the part suitable for use as an input buffer for popular 8-bit, 10-bit, 12-bit and 14-bit mega-sample ADCs.

The input common mode range extends 200 mV beyond the supply rails. On a single 5V supply with a ground terminated 150 $\Omega$  load the output swings to within 37 mV of the ground rail, while a mid-rail terminated 1 k $\Omega$  load will swing to 77 mV of either rail, providing true single supply operation and maximum signal dynamic range on low power rails. The amplifier output will source and sink 35 mA and drive up to 30 pF loads without the need for external compensation.

The LMH6619Q is offered in the 8-Pin SOIC package.

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PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

### **Typical Application**







These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### Absolute Maximum Ratings<sup>(1)</sup>

•	
ESD Tolerance <sup>(2)</sup>	
Human Body Model	
For input pins only	2000V
For all other pins	2000V
Machine Model	200V
Supply Voltage ( $V_S = V^+ - V^-$ )	12V
Junction Temperature <sup>(3)</sup>	150°C max
Storage Temperature Range	–65°C to 150°C
Soldering Information:	
See product folder at www.ti.com and www.ti.com/ lit/an/snoa549c /snoa549c.pdf.	

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics.

(2) Human Body Model, applicable std. MIL-STD-883, Method 3015.7. Machine Model, applicable std. JESD22-A115-A (ESD MM std. of JEDEC)Field-Induced Charge-Device Model, applicable std. JESD22-C101-C (ESD FICDM std. of JEDEC).

(3) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $\theta_{JA}$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} - T_A)/\theta_{JA}$ . All numbers apply for packages soldered directly onto a PC Board.

## **Operating Ratings** <sup>(1)</sup>

Supply Voltage ( $V_S = V^+ - V^-$ )	2.7V to 11V
Ambient Temperature Range <sup>(2)</sup>	−40°C to +105°C
Package Thermal Resistance (θ <sub>JA</sub> )	
8-Pin SOIC	160°C/W

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics.

(2) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $\theta_{JA}$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} - T_A)/|\theta_{JA}|$ . All numbers apply for packages soldered directly onto a PC Board.



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### +3V Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for  $T_J = +25^{\circ}C$ ,  $V^+ = 3V$ ,  $V^- = 0V$ ,  $V_{CM} = V_O = V^+/2$ ,  $A_V = +1$  ( $R_F = 0\Omega$ ), otherwise  $R_F = 2 \ k\Omega$  for  $A_V \neq +1$ ,  $R_L = 1 \ k\Omega \parallel 5 \ pF$ . **Boldface** Limits apply at temperature extremes. <sup>(1)</sup>

Symbol	Parameter	Condition	Min Typ Max (2) (3) (2)		Max (2)	Units
Frequen	cy Domain Response			1	I	
SSBW	-3 dB Bandwidth Small Signal	$A_V = 1$ , $R_L = 1$ k $\Omega$ , $V_{OUT} = 0.2$ $V_{PP}$		120		Units MHz MHz MHz dB MHz % deg 0 deg 0 v/µs ns 0 dBc nv//√Hz pA/√Hz dB
		$A_V = 2, -1, R_L = 1 \text{ k}\Omega, V_{OUT} = 0.2 V_{PP}$		56		MHZ
GBW	Gain Bandwidth		55	63		MHz
LSBW	-3 dB Bandwidth Large Signal	$A_V = 1, \ R_L = 1 \ k\Omega, \ V_{OUT} = 2 \ V_{PP}$		13		MU-7
		$\begin{tabular}{ c c c c c c } \hline Condition & Min (2) & Typ (8) & Max (2) \\ \hline Musc (2) & M$				
Peak	Peaking	$A_V = 1, C_L = 5 \text{ pF}$		1.5		dB
0.1 dBBW	0.1 dB Bandwidth				MHz	
DG	Differential Gain				%	
DP	Differential Phase	$A_V$ = +2, 4.43 MHz, 0.6V < $V_{OUT}$ < 2V, $R_L$ = 150 $\Omega$ to V^+/2		0.1		deg
Time Do	main Response					
t <sub>r</sub> /t <sub>f</sub>	Rise & Fall Time	2V Step, $A_V = 1$		36		ns
SR	Slew Rate	2V Step, $A_V = 1$	36	46		V/µs
t <sub>s_0.1</sub>	0.1% Settling Time	2V Step, $A_V = -1$		90	ns	
t <sub>s_0.01</sub>	0.01% Settling Time	2V Step, $A_V = -1$		120		115
Noise an	d Distortion Performance					
SFDR Spurious Free Dynamic Range	$f_C = 100 \text{ kHz},  V_{OUT} = 2  V_{PP},  R_L = 1  k\Omega$		100			
	FDR Spurious Free Dynamic Range	$f_{C}$ = 1 MHz, $V_{OUT}$ = 2 $V_{PP}$ , $R_{L}$ = 1 k $\Omega$		61		dBc
		$f_C = 5 \text{ MHz},  V_{OUT} = 2  V_{PP},  \text{R}_L = 1  \text{k} \Omega$		47		
e <sub>n</sub>	Input Voltage Noise Density	f = 100 kHz	10			nV/√Hz
i <sub>n</sub>	Input Current Noise Density	f = 100 kHz	1			pA/√Hz
СТ	Crosstalk	f = 5 MHz, V <sub>IN</sub> = 2 V <sub>PP</sub> 80			dB	
Input, DO	C Performance					
V <sub>OS</sub>	Input Offset Voltage	$V_{CM} = 0.5V$ (pnp active) $V_{CM} = 2.5V$ (npn active)		0.1	±0.75 <b>±1.3</b>	mV
TCV <sub>OS</sub>	Input Offset Voltage Temperature Drift	(4)		0.8		µV/°C
I <sub>B</sub>	Input Bias Current	$V_{CM} = 0.5V$ (pnp active)		-1.4	-2.6	
		$V_{CM} = 2.5V$ (npn active)		+1.0	+1.8	μΑ
I <sub>OS</sub>	Input Offset Current			0.01	±0.27	μA
C <sub>IN</sub>	Input Capacitance			1.5		pF
R <sub>IN</sub>	Input Resistance			8		MΩ
CMVR	Common Mode Voltage Range	DC, CMRR ≥ 65 dB	-0.2		3.2	V
CMRR	Common Mode Rejection Ratio	$V_{\text{CM}}$ Stepped from –0.1V to 1.4V	78	96		dP
		V <sub>CM</sub> Stepped from 2.0V to 3.1V	81	107		uD
A <sub>OL</sub>	Open Loop Voltage Gain	$R_L = 1 \text{ k}\Omega \text{ to } +2.7 \text{V} \text{ or } +0.3 \text{V}$	85	98		dP
		$R_{L} = 150\Omega$ to +2.6V or +0.4V	76	82		uD
Output D	OC Characteristics					

(1) Boldface limits apply to temperature range of -40°C to 105°C

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.

(4) Voltage average drift is determined by dividing the change in  $V_{OS}$  by temperature change.

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<sup>(2)</sup> Limits are 100% production tested at 25°C. Limits over the operating temperature range are guaranteed through correlations using the Statistical Quality Control (SQC) method.

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## +3V Electrical Characteristics (continued)

Unless otherwise specified, all limits are guaranteed for  $T_J = +25^{\circ}C$ ,  $V^+ = 3V$ ,  $V^- = 0V$ ,  $V_{CM} = V_O = V^+/2$ ,  $A_V = +1$  ( $R_F = 0\Omega$ ), otherwise  $R_F = 2 k\Omega$  for  $A_V \neq +1$ ,  $R_L = 1 k\Omega \parallel 5 pF$ . **Boldface** Limits apply at temperature extremes.<sup>(1)</sup>

Symbol	Parameter	Condition	Min (2)	Тур (3)	Max (2)	Units
V <sub>OUT</sub>	Output Voltage Swing High (Voltage from V <sup>+</sup> Supply Rail)	$R_L = 1 \ k\Omega$ to V <sup>+</sup> /2		50	56 <b>62</b>	
		$R_L = 150\Omega$ to V <sup>+</sup> /2		160	172 <b>198</b>	
	Output Voltage Swing Low (Voltage from V <sup>-</sup> Supply Rail)	$R_L = 1 \ k\Omega$ to V <sup>+</sup> /2		62	68 <b>76</b>	mV from either rail
		$R_L = 150\Omega$ to V <sup>+</sup> /2		175	189 <b>222</b>	
		$R_L = 150\Omega$ to V <sup>-</sup>		34	44 <b>48</b>	
I <sub>OUT</sub>	Linear Output Current	$V_{OUT} = V^{+}/2^{(5)}$	±25	±35		mA
R <sub>OUT</sub>	Output Resistance	f = 1 MHz		0.17		Ω
Power S	upply Performance					
PSRR	Power Supply Rejection Ratio	DC, $V_{CM} = 0.5V$ , $V_S = 2.7V$ to 11V	84	104		dB
I <sub>S</sub>	Supply Current (per channel)	R <sub>L</sub> = ∞		1.2	1.5 <b>1.75</b>	

(5) Do not short circuit the output. Continuous source or sink currents larger than the I<sub>OUT</sub> typical are not recommended as it may damage the part.



### +5V Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for  $T_J = +25^{\circ}C$ ,  $V^+ = 5V$ ,  $V^- = 0V$ ,  $V_{CM} = V_O = V^+/2$ ,  $A_V = +1$  ( $R_F = 0\Omega$ ), otherwise  $R_F = 2 \ k\Omega$  for  $A_V \neq +1$ ,  $R_L = 1 \ k\Omega \parallel 5 \ pF$ . **Boldface** Limits apply at temperature extremes.

Symbol	Parameter	Condition	Min (1)	Typ Max (2) (1)		Units		
Frequen	cy Domain Response							
SSBW	-3 dB Bandwidth Small Signal	$A_V = 1, R_L = 1 \ k\Omega, V_{OUT} = 0.2 \ V_{PP}$		130				
		$A_V = 2, -1, R_L = 1 \text{ k}\Omega, V_{OUT} = 0.2 V_{PP}$		53		MHz		
GBW	Gain Bandwidth		54	57	57			
LSBW	-3 dB Bandwidth Large Signal	$A_V = 1, R_L = 1 \ k\Omega, V_{OUT} = 2 \ V_{PP}$		15		MU-		
		$A_V = 2$ , $R_L = 150\Omega$ , $V_{OUT} = 2 V_{PP}$		15				
Peak	Peaking	$A_V = 1, C_L = 5 \text{ pF}$		0.5		dB		
0.1 dBBW	0.1 dB Bandwidth			15		MHz		
DG	Differential Gain			0.1		%		
DP	Differential Phase				deg			
Time Do	main Response			1				
t <sub>r</sub> /t <sub>f</sub>	Rise & Fall Time	2V Step, $A_V = 1$		30		ns		
SR	Slew Rate	2V Step, $A_V = 1$	44	55		V/µs		
t <sub>s_0.1</sub>	0.1% Settling Time	2V Step, $A_V = -1$		90	ns			
t <sub>s_0.01</sub>	0.01% Settling Time	2V Step, $A_V = -1$		120		110		
Distortio	n and Noise Performance			ſ	[	[		
SFDR Spurious Fi	Spurious Free Dynamic Range	$f_C = 100 \text{ kHz}, V_{OUT} = 2 \text{ V}_{PP}, R_L = 1 \text{ k}\Omega$		100				
		$f_{C}$ = 1 MHz, $V_{OUT}$ = 2 $V_{PP}$ , $R_{L}$ = 1 k $\Omega$		88		dBc		
		$f_C = 5 \text{ MHz},  V_O = 2  V_{PP},  R_L = 1  k\Omega$		61				
e <sub>n</sub>	Input Voltage Noise Density	f = 100 kHz		10		nV/√Hz		
i <sub>n</sub>	Input Current Noise Density	f = 100 kHz		1		pA/√Hz		
СТ	Crosstalk	$f = 5 \text{ MHz}, V_{IN} = 2 V_{PP}$		80		dB		
Input, DC	C Performance							
V <sub>OS</sub>	Input Offset Voltage	$V_{CM} = 0.5V$ (pnp active) $V_{CM} = 4.5V$ (npn active)		0.1	±0.75 <b>±1.3</b>	mV		
TCV <sub>OS</sub>	Input Offset Voltage Temperature Drift	(3)		0.8		µV/°C		
I <sub>B</sub>	Input Bias Current	$V_{CM} = 0.5V$ (pnp active)		-1.5	-2.4			
		$V_{CM} = 4.5V$ (npn active)		+1.0	+1.9	μΛ		
I <sub>OS</sub>	Input Offset Current			0.01	±0.26	μA		
CIN	Input Capacitance			1.5		pF		
R <sub>IN</sub>	Input Resistance			8		MΩ		
CMVR	Common Mode Voltage Range	DC, CMRR ≥ 65 dB	-0.2		5.2	V		
CMRR	Common Mode Rejection Ratio	$V_{\text{CM}}$ Stepped from –0.1V to 3.4V	81	98		dR		
		$V_{\text{CM}}$ Stepped from 4.0V to 5.1V	84	108		uD		
A <sub>OL</sub>	Open Loop Voltage Gain	$R_L = 1 \ k\Omega$ to +4.6V or +0.4V	84	100		dB		
		$R_L = 150\Omega$ to +4.5V or +0.5V	78	83		uВ		
Output D	Output DC Characteristics							

(1) Limits are 100% production tested at 25°C. Limits over the operating temperature range are guaranteed through correlations using the Statistical Quality Control (SQC) method.

(2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.

(3) Voltage average drift is determined by dividing the change in  $V_{OS}$  by temperature change.

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## +5V Electrical Characteristics (continued)

Unless otherwise specified, all limits are guaranteed for  $T_J = +25^{\circ}C$ ,  $V^+ = 5V$ ,  $V^- = 0V$ ,  $V_{CM} = V_O = V^+/2$ ,  $A_V = +1$  ( $R_F = 0\Omega$ ), otherwise  $R_F = 2 k\Omega$  for  $A_V \neq +1$ ,  $R_L = 1 k\Omega \parallel 5 pF$ . **Boldface** Limits apply at temperature extremes.

Symbol	Parameter	Condition	Min (1)	Тур (2)	Max (1)	Units
V <sub>OUT</sub>	Output Voltage Swing High Voltage from V <sup>+</sup> Supply Rail)	$R_L = 1 \ k\Omega$ to V <sup>+</sup> /2		60	73 <b>82</b>	
		$R_L = 150\Omega$ to V <sup>+</sup> /2		230	255 <b>295</b>	
	Output Voltage Swing Low Voltage from V <sup>-</sup> Supply Rail)	$R_L = 1 \ k\Omega$ to V <sup>+</sup> /2		77	85 <b>98</b>	mV from either rail
		$R_L = 150\Omega$ to V <sup>+</sup> /2		255	275 <b>326</b>	
		$R_L = 150\Omega$ to V <sup>-</sup>		37	48 <b>50</b>	
I <sub>OUT</sub>	Linear Output Current	$V_{OUT} = V^{+}/2^{(4)}$	±25	±35		mA
R <sub>OUT</sub>	Output Resistance	f = 1 MHz		0.17		Ω
Power S	upply Performance	·				
PSRR	Power Supply Rejection Ratio	DC, $V_{CM} = 0.5V$ , $V_S = 2.7V$ to 11V	84	104		dB
I <sub>S</sub>	Supply Current (per channel)	R <sub>L</sub> = ∞		1.3	1.5 <b>1.75</b>	

(4) Do not short circuit the output. Continuous source or sink currents larger than the I<sub>OUT</sub> typical are not recommended as it may damage the part.



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### ±5V Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for  $T_J = +25^{\circ}C$ ,  $V^+ = 5V$ ,  $V^- = -5V$ ,  $V_{CM} = V_O = 0V$ ,  $A_V = +1$  ( $R_F = 0\Omega$ ), otherwise  $R_F = 2 \ k\Omega$  for  $A_V \neq +1$ ,  $R_L = 1 \ k\Omega \parallel 5 \ pF$ . **Boldface** Limits apply at temperature extremes.

Symbol	Parameter	Condition	Min Typ Max (1) (2) (1)		Max (1)	Units	
Frequen	cy Domain Response				1		
SSBW	-3 dB Bandwidth Small Signal	$A_V = 1, R_L = 1 \ k\Omega, V_{OUT} = 0.2 \ V_{PP}$		140			
		$A_V = 2, -1, R_L = 1 \text{ k}\Omega, V_{OUT} = 0.2 V_{PP}$		53		MHz	
GBW	Gain Bandwidth		54	58		MHz	
LSBW	-3 dB Bandwidth Large Signal	$A_V = 1, R_L = 1 \text{ k}\Omega, V_{OUT} = 2 V_{PP}$		16		N41 I-	
		$A_V$ = 2, $R_L$ = 150 $\Omega$ , $V_{OUT}$ = 2 $V_{PP}$		15		IVITZ	
Peak	Peaking	$A_V = 1, C_L = 5 \text{ pF}$		0.05		dB	
0.1 dBBW	0.1 dB Bandwidth			15		MHz	
DG	Differential Gain			0.1		%	
DP	Differential Phase			0.1		deg	
Time Do	main Response					·	
t <sub>r</sub> /t <sub>f</sub>	Rise & Fall Time	2V Step, $A_V = 1$		30		ns	
SR	Slew Rate	2V Step, $A_V = 1$	45	57		V/µs	
t <sub>s_0.1</sub>	0.1% Settling Time	2V Step, $A_V = -1$		90	ns		
t <sub>s_0.01</sub>	0.01% Settling Time	2V Step, $A_V = -1$		120	115		
Noise an	d Distortion Performance						
SFDR Spurious Free D	Spurious Free Dynamic Range	$f_C = 100 \text{ kHz},  V_{OUT} = 2  V_{PP},  \text{R}_L = 1  \text{k}\Omega$		100			
		$f_C = 1 \text{ MHz},  V_{OUT} = 2  V_{PP},  R_L = 1  k\Omega$		88		dBc	
		$f_C = 5 \text{ MHz},  V_{OUT} = 2  V_{PP},  R_L = 1  k\Omega$		70			
e <sub>n</sub>	Input Voltage Noise Density	f = 100 kHz		10		nV/√Hz	
i <sub>n</sub>	Input Current Noise Density	f = 100 kHz		1		pA/√Hz	
СТ	Crosstalk	$f = 5 \text{ MHz}, V_{IN} = 2 V_{PP}$		80		dB	
Input DC	Performance						
V <sub>OS</sub>	Input Offset Voltage	$V_{CM} = -4.5V$ (pnp active) $V_{CM} = 4.5V$ (npn active)		0.1	±0.75 <b>±1.3</b>	mV	
TCV <sub>OS</sub>	Input Offset Voltage Temperature Drift	(3)		0.9		µV/°C	
I <sub>B</sub>	Input Bias Current	$V_{CM} = -4.5V$ (pnp active)		-1.5	-2.4		
		$V_{CM} = 4.5V$ (npn active)		+1.0	+1.9	μΛ	
I <sub>OS</sub>	Input Offset Current			0.01	±0.26	μA	
C <sub>IN</sub>	Input Capacitance			1.5		pF	
R <sub>IN</sub>	Input Resistance			8		MΩ	
CMVR	Common Mode Voltage Range	DC, CMRR ≥ 65 dB	-5.2		5.2	V	
CMRR	Common Mode Rejection Ratio	$V_{\text{CM}}$ Stepped from –5.1V to 3.4V	84	100		dB	
		$V_{\text{CM}}$ Stepped from 4.0V to 5.1V	83	108		uВ	
A <sub>OL</sub>	Open Loop Voltage Gain	$R_L = 1 k\Omega$ to +4.6V or -4.6V	86	95		dB	
		$R_L = 150\Omega$ to +4.3V or -4.3V	79	84		αB	
Output DC Characteristics							

(1) Limits are 100% production tested at 25°C. Limits over the operating temperature range are guaranteed through correlations using the Statistical Quality Control (SQC) method.

(2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.

(3) Voltage average drift is determined by dividing the change in  $V_{OS}$  by temperature change.

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## ±5V Electrical Characteristics (continued)

Unless otherwise specified, all limits are guaranteed for  $T_J = +25^{\circ}C$ ,  $V^+ = 5V$ ,  $V^- = -5V$ ,  $V_{CM} = V_O = 0V$ ,  $A_V = +1$  ( $R_F = 0\Omega$ ), otherwise  $R_F = 2 k\Omega$  for  $A_V \neq +1$ ,  $R_L = 1 k\Omega \parallel 5 pF$ . **Boldface** Limits apply at temperature extremes.

Symbol	Parameter	Condition	Min (1)	Тур (2)	Max (1)	Units
V <sub>OUT</sub>	Output Voltage Swing High (Voltage from V <sup>+</sup> Supply Rail)	$R_L = 1 \ k\Omega$ to GND		100	111 <b>126</b>	
		$R_L = 150\Omega$ to GND		430	457 <b>526</b>	
Output Voltage Swing Low (Voltage from V <sup>-</sup> Supply Rail)	$R_L = 1 \ k\Omega$ to GND		115	126 <b>141</b>	mV from either rail	
		$R_L = 150\Omega$ to GND		450	484 <b>569</b>	
		$R_L = 150\Omega$ to V <sup>-</sup>		45	61 <b>62</b>	
I <sub>OUT</sub>	Linear Output Current	$V_{OUT} = V^{+}/2^{(4)}$	±25	±35		mA
R <sub>OUT</sub>	Output Resistance	f = 1 MHz		0.17		Ω
Power S	upply Performance	·				
PSRR	Power Supply Rejection Ratio	DC, $V_{CM} = -4.5V$ , $V_{S} = 2.7V$ to 11V	84	104		dB
I <sub>S</sub>	Supply Current (per channel)	R <sub>L</sub> = ∞		1.45	1.65 <b>2.0</b>	

(4) Do not short circuit the output. Continuous source or sink currents larger than the I<sub>OUT</sub> typical are not recommended as it may damage the part.

### **Connection Diagram**

#### 8-Pin SOIC



Figure 2. Top View



# LMH6619Q

#### SNOSC78A -JUNE 2012-REVISED NOVEMBER 2012

= +2.5V

1000

1000

1000

V = -2.5V

100

= +1.5V

100

-40°C

FREQUENCY (MHz)

12

FREQUENCY (MHz)

100

10

Various Supplies

V<sup>+</sup> = +1.5V

 $V^{+} = +5V$ 

10

= +5V.

= -5\

10

FREQUENCY (MHz)

Various Supplies

= -5V

11111

v

-1.5V



**PRODUCT PREVIEW** 

SNOSC78A-JUNE 2012-REVISED NOVEMBER 2012

**EXAS** NSTRUMENTS

+5\

-5\ î î î î î î î

= +2.5\

-2.5

100

100

= +1.5

V<sup>+</sup> = +5∖

= -5V 

10

v = -1.5V

= +2 5\

= -2.5V

1

vs.

1000

1000



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10

Submit Documentation Feedback





1500

HD2, RI

HD3

7 8 9 10

+2, HD3

V<sup>+</sup> = +2.5V

V = -2.5V

1 kΩ

10



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10



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HD2



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THD

vs.

**Output Swing** 

5 MHz

10 MH



 $V^{+} = +2.5V$ V = -2.5V A<sub>V</sub> = -1  $R_L = 1 \ k\Omega$ 1 MHz 500 kHz 100 kH 1 2 4 5 3 OUTPUT SWING (VPP) **Input Noise** vs. Frequency 1000 = +2.5 -2.5V CURRENT NOISE (pA/VHz) 100 OI TAGE NOISE 0 CURRENT NOISE 100 1k 100k 1M 10M 10k FREQUENCY (Hz) Vos



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# **Typical Performance Characteristics (continued)**

ł

125°C

12



125°C

√ = -0.5V .V<sub>S</sub> = V<sup>+</sup> - V<sup>-</sup>

 $V_{CM} = 0.5V$ 

10

 $R_L = 150\Omega$  to

MID-RAIL

10

12

125°C

8

12

ls

vs.

٧s

25°C

40%

4 6 8

40℃

4

-2.5V

250

6

Vs (V)

vs.

Frequency A<sub>V</sub> = +1

0.1

0.01

FREQUENCY (MHz)

1

V<sub>S</sub> (V)

VOUT

vs.

٧s



**PRODUCT PREVIEW** 

100

10

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Texas **NSTRUMENTS** 





# LMH6619Q



#### SNOSC78A – JUNE 2012 – REVISED NOVEMBER 2012



At  $T_J = 25^{\circ}C$ ,  $A_V = +1$  ( $R_F = 0\Omega$ ), otherwise  $R_F = 2 \text{ k}\Omega$  for  $A_V \neq +1$ , unless otherwise specified.





## Application Information

The LMH6619Q is based on National Semiconductor's proprietary VIP10 dielectrically isolated bipolar process. This device family architecture features the following:

• Complimentary bipolar devices with exceptionally high ft (~8 GHz) even under low supply voltage (2.7V) and

100 ns/DIV



**Fexas** 

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low bias current.

- Common emitter push-push output stage. This architecture allows the output to reach within millivolts of either supply rail.
- Consistent performance from any supply voltage (2.7V 11V) with little variation with supply voltage for the most important specifications (e.g. BW, SR, I<sub>OUT</sub>.)
- Significant power saving compared to competitive devices on the market with similar performance.

With 3V supplies and a common mode input voltage range that extends beyond either supply rail, the LMH6619Q is well suited to many low voltage/low power applications. Even with 3V supplies, the -3 dB BW (at A<sub>V</sub> = +1) is typically 120 MHz.

The LMH6619Q is designed to avoid output phase reversal. With input over-drive, the output is kept near the supply rail (or as close to it as mandated by the closed loop gain setting and the input voltage). Figure 3 shows the input and output voltage when the input voltage significantly exceeds the supply voltages.



Figure 3. Input and Output Shown with CMVR Exceeded

### SINGLE TO DIFFERENTIAL ADC DRIVER

Figure 4 shows the LMH6619Q used to drive a differential ADC with a single-ended input. The ADC121S625 is a fully differential 12-bit ADC. Table 1 shows the performance data of the LMH6619Q and the ADC121S625.



Figure 4. LMH6619Q Driving an ADC121S625

Parameter	Measured Value
Signal Frequency	10 kHz
Signal Amplitude	2.5V



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Parameter	Measured Value
SINAD	67.9 dB
SNR	68.29 dB
THD	-78.6 dB
SFDR	75.0 dB
ENOB	11.0 bits

Table 1.	Performance	Data for the	Single to	Differential	ADC Driver	(continued)	
		Data ioi tiio	•				

### DIFFERENTIAL ADC DRIVER

Its low noise and wide bandwidth make the LMH6619Q an excellent choice for driving a 12-bit ADC. Figure 5 shows the LMH6619Q driving an ADC121S705. The ADC121S705 is a fully differential 12-bit ADC.The LMH6619Q is set up in a 2nd order multiple-feedback configuration with a gain of -1. The -3 dB point is at 500 kHz and the -0.01 dB point is at 100 kHz. The 22 $\Omega$  resistor and 390 pF capacitor form an antialiasing filter for the ADC121S705. The capacitor also stores and delivers charge to the switched capacitor input of the ADC. The capacitive load on the LMH6619Q created by the 390 pF capacitor is decreased by the 22 $\Omega$  resistor. Table 2 shows the performance data.





#### Table 2. Performance Data for the Differential ADC Driver

Parameter	Measured Value
Signal Frequency	100 kHz
SINAD	71.5 dB
SNR	71.87 dB
THD	-82.4 dB

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|--|

Parameter	Measured Value
SFDR	90.97 dB
ENOB	11.6 bits

### DC LEVEL SHIFTING

Often a signal must be both amplified and level shifted while using a single supply for the op amp. The circuit in Figure 6 can do both of these tasks. The procedure for specifying the resistor values is as follows.

- 1. Determine the input voltage.
- 2. Calculate the input voltage midpoint,  $V_{INMID} = V_{INMIN} + (V_{INMAX} V_{INMIN})/2$ .
- 3. Determine the output voltage needed.
- 4. Calculate the output voltage midpoint,  $V_{OUTMID} = V_{OUTMIN} + (V_{OUTMAX} V_{OUTMIN})/2$ .
- 5. Calculate the gain needed, gain =  $(V_{OUTMAX} V_{OUTMIN})/(V_{INMAX} V_{INMIN})$
- 6. Calculate the amount the voltage needs to be shifted from input to output,  $\Delta V_{OUT} = V_{OUTMID} \text{gain x } V_{INMID}$ .
- 7. Set the supply voltage to be used.
- 8. Calculate the noise gain, noise gain = gain +  $\Delta V_{OUT}/V_S$ .
- 9. Set R<sub>F</sub>.
- 10. Calculate  $R_1$ ,  $R_1 = R_F$ /gain.
- 11. Calculate  $R_2$ ,  $R_2 = R_F/(noise gain-gain)$ .
- 12. Calculate  $R_G$ ,  $R_G = R_F/(noise gain 1)$ .

Check that both the  $V_{IN}$  and  $V_{OUT}$  are within the voltage ranges of the LMH6619Q.

The following example is for a  $V_{IN}$  of 0V to 1V with a  $V_{OUT}$  of 2V to 4V.

1.  $V_{IN} = 0V$  to 1V

PRODUCT PREVIEW

- 2.  $V_{INMID} = 0V + (1V 0V)/2 = 0.5V$
- 3.  $V_{OUT} = 2V$  to 4V
- 4.  $V_{OUTMID} = 2V + (4V 2V)/2 = 3V$
- 5. Gain = (4V 2V)/(1V 0V) = 2

6. 
$$\Delta V_{OUT} = 3V - 2 \times 0.5V = 2$$

- 7. For the example the supply voltage will be +5V.
- 8. Noise gain = 2 + 2/5V = 2.4
- 9.  $R_F = 2 k\Omega$
- 10.  $R_1 = 2 k\Omega/2 = 1 k\Omega$
- 11.  $R_2 = 2 k\Omega/(2.4-2) = 5 k\Omega$
- 12.  $R_G = 2 k\Omega/(2.4 1) = 1.43 k\Omega$



Figure 6. DC Level Shifting



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### 4<sup>th</sup> ORDER MULTIPLE FEEDBACK LOW-PASS FILTER

Figure 7 shows the LMH6619Q used as the amplifier in a multiple feedback low pass filter. This filter is set up to have a gain of +1 and a -3 dB point of 1 MHz. Values can be determined by using the WEBENCH<sup>®</sup> Active Filter Designer found at amplifiers.national.com.



Figure 7. 4<sup>th</sup> Order Multiple Feedback Low-Pass Filter

#### CURRENT SENSE AMPLIFIER

With it's rail-to-rail input and output capability, low V<sub>OS</sub>, and low I<sub>B</sub> the LMH6619Q is an ideal choice for a current sense amplifier application. Figure 8 shows the schematic of the LMH6619Q set up in a low-side sense configuration which provides a conversion gain of 2V/A. Voltage error due to V<sub>OS</sub> can be calculated to be V<sub>OS</sub> x (1 + R<sub>F</sub>/R<sub>G</sub>) or 0.6 mV x 21 = 12.6 mV. Voltage error due to I<sub>O</sub> is I<sub>O</sub> x R<sub>F</sub> or 0.26  $\mu$ A x 1 k $\Omega$  = 0.26 mV. Hence total voltage error is 12.6 mV + 0.26 mV or 12.86 mV which translates into a current error of 12.86 mV/(2 V/A) = 6.43 mA.



Figure 8. Current Sense Amplifier

#### TRANSIMPEDANCE AMPLIFIER

By definition, a photodiode produces either a current or voltage output from exposure to a light source. A Transimpedance Amplifier (TIA) is utilized to convert this low-level current to a usable voltage signal. The TIA often will need to be compensated to insure proper operation.



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#### Figure 9. Photodiode Modeled with Capacitance Elements

Figure 9 shows the LMH6619Q modeled with photodiode and the internal op amp capacitances. The LMH6619Q allows circuit operation of a low intensity light due to its low input bias current by using larger values of gain (R<sub>F</sub>). The total capacitance (C<sub>T</sub>) on the inverting terminal of the op amp includes the photodiode capacitance (C<sub>PD</sub>) and the input capacitance of the op amp ( $C_{IN}$ ). This total capacitance ( $C_T$ ) plays an important role in the stability of the circuit. The noise gain of this circuit determines the stability and is defined by:

$$NG = \frac{1 + sR_F (C_T + C_F)}{1 + sC_FR_F}$$
(1)
$$Where, f_Z \cong \frac{1}{2\pi R_FC_T} \text{ and } f_P = \frac{1}{2\pi R_FC_F}$$
(2)



Figure 10. Bode Plot of Noise Gain Intersecting with Op Amp Open-Loop Gain

Figure 10 shows the bode plot of the noise gain intersecting the op amp open loop gain. With larger values of gain, C<sub>T</sub> and R<sub>F</sub> create a zero in the transfer function. At higher frequencies the circuit can become unstable due to excess phase shift around the loop.

A pole at  $f_P$  in the noise gain function is created by placing a feedback capacitor ( $C_F$ ) across  $R_F$ . The noise gain slope is flattened by choosing an appropriate value of C<sub>F</sub> for optimum performance.

Theoretical expressions for calculating the optimum value of  $C_F$  and the expected -3 dB bandwidth are:

$$C_{F} = \sqrt{\frac{C_{T}}{2\pi R_{F}(GBWP)}}$$

$$f_{.3 dB} = \sqrt{\frac{GBWP}{2\pi R_{F}C_{T}}}$$
(3)

(4)

Equation 4 indicates that the -3 dB bandwidth of the TIA is inversely proportional to the feedback resistor. Therefore, if the bandwidth is important then the best approach would be to have a moderate transimpedance gain stage followed by a broadband voltage gain stage.

Table 3 shows the measurement results of the LMH6619Q with different photodiodes having various capacitances ( $C_{PD}$ ) and a feedback resistance ( $R_{F}$ ) of 1 k $\Omega$ .

C <sub>PD</sub>	CT	C <sub>F CAL</sub>	C <sub>F USED</sub>	f –3 dB CAL	f <sub>−3 dB MEAS</sub>	Peaking				
(pF)	(pF)	(pF)	(pF)	(MHz)	(MHz)	(dB)				
22	24	7.7	5.6	23.7	20	0.9				
47	49	10.9	10	16.6	15.2	0.8				
100	102	15.8	15	11.5	10.8	0.9				
222	224	23.4	18	7.81	8	2.9				

Table 3.	TIA	(Figure 1)	Compensation and Perfo	prmance Results
				manee neguita

Figure 11 shows the frequency response for the various photodiodes in Table 3.



Figure 11. Frequency Response for Various Photodiode and Feedback Capacitors

When analyzing the noise at the output of the TIA, it is important to note that the various noise sources (i.e. op amp noise voltage, feedback resistor thermal noise, input noise current, photodiode noise current) do not all operate over the same frequency band. Therefore, when the noise at the output is calculated, this should be taken into account. The op amp noise voltage will be gained up in the region between the noise gain's zero and pole ( $f_Z$  and  $f_P$  in Figure 10). The higher the values of  $R_F$  and  $C_T$ , the sooner the noise gain peaking starts and therefore its contribution to the total output noise will be larger. It is obvious to note that it is advantageous to minimize  $C_{IN}$  by proper choice of op amp or by applying a reverse bias across the diode at the expense of excess dark current and noise.

#### DIFFERENTIAL CABLE DRIVER FOR NTSC VIDEO

The LMH6619Q can be used to drive an NTSC video signal on a twisted-pair cable. Figure 12 shows the schematic of a differential cable driver for NTSC video. This circuit can be used to transmit the signal from a camera over a twisted pair to a monitor or display located a distance.  $C_1$  and  $C_2$  are used to AC couple the video signal into the LMH6619Q. The two amplifiers of the LMH6619Q are set to a gain of 2 to compensate for the 75 $\Omega$  back termination resistors on the outputs. The LMH6619Q is set to a gain of 1. Because of the DC bias the output of the LMH6619Q is AC coupled. Most monitors and displays will accept AC coupled inputs.



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## **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		uly	(2)	(6)	(3)		(4/5)	
LMH6619QMAK/NOPB	ACTIVE	SOIC	D	8	95	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 105	LMH66 19QMA	Samples
LMH6619QMAKE/NOPB	ACTIVE	SOIC	D	8	250	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 105	LMH66 19QMA	Samples
LMH6619QMAKX/NOPB	ACTIVE	SOIC	D	8	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 105	LMH66 19QMA	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

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<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# PACKAGE OPTION ADDENDUM

10-Dec-2020

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LMH6619-Q1 :

Catalog: LMH6619

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

# PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMH6619QMAKE/NOPB	SOIC	D	8	250	178.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMH6619QMAKX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1



# PACKAGE MATERIALS INFORMATION

5-Jan-2022



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMH6619QMAKE/NOPB	SOIC	D	8	250	208.0	191.0	35.0
LMH6619QMAKX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0



5-Jan-2022

# TUBE



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
LMH6619QMAK/NOPB	D	SOIC	8	95	495	8	4064	3.05

# D0008A



# **PACKAGE OUTLINE**

# SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



#### NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.

- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



# D0008A

# **EXAMPLE BOARD LAYOUT**

# SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# D0008A

# **EXAMPLE STENCIL DESIGN**

# SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.



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